Product/Process Change Notice - PCN 25_0156 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. An acceptance or concern response should be submitted to ADI promptly. Any requests for samples of changed material or additional information must be made within 30 days of the notification. In accordance with JEDEC Standard 046, customers should acknowledge receipt of the PCN within 30 days of the PCN delivery. ADI contact information is listed below. Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change. After the acknowledgment, a lack of additional requests within 90 days constitutes acceptance of the change.

PCN Title:	Qualification of Wafer Fabrication Site Analog Devices, Inc. Camas WA for HVBP1 Products
Publication Date:	01-Oct-2025
Effectivity Date:	03-Jan-2026 *(the earliest date that a customer could expect to receive changed material)*
Revision Description:	Initial Release.

Description Of Change:

Qualification of Wafer Fabrication Site Analog Devices, Inc. Camas WA for HVBP1 Products.

Reason For Change:

Leveraging the existing qualified process at our Analog Devices Camas, WA Fab ensures a reliable and continuous supply for our customers securing their needs well into the future.

The affected products will be manufactured using ADI specified manufacturing flows, materials, process controls, and monitors ensuring no degradation of quality and reliability performance.

Impact of the change (positive or negative) on fit, form, function & reliability:

There is no expected impact to fit, form, function or reliability.

Product Identification: *(this section will describe how to identify the changed material)*

Traceability will be maintained via standard ADI lot traceability.

Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results.

Supporting Documents:

Attachment 1: Type: Qualification Results Summary

ADI_PCN_25_0156_Rev_-_Qualification of ADI Camas Wafer Fab HVBP1 Process.pdf

Note: If applicable, the device material declaration will be updated due to material change.

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

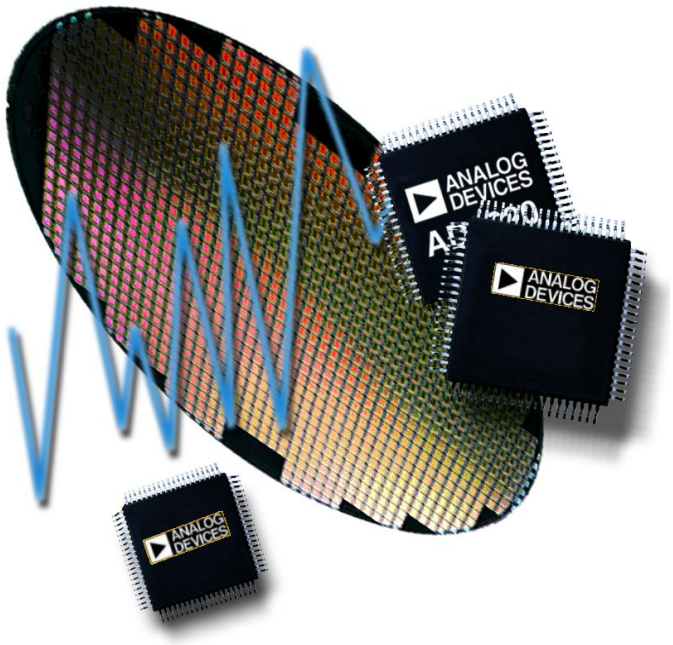
Americas:	Europe:	Japan:	Korea:	Rest of Asia:

Appendix A - Affected ADI Models:

Added Parts On This Revision - Product Family / Model Number (126)

AD8510 / AD8510ARMZ	AD8510 / AD8510ARMZ-REEL	AD8510 / AD8510ARZ	AD8510 / AD8510ARZ-REEL	AD8510 / AD8510ARZ-REEL7
AD8510 / AD8510BRZ	AD8510 / AD8510BRZ-REEL	AD8510 / AD8510BRZ-REEL7	AD8512 / AD8512ARMZ	AD8512 / AD8512ARMZ-REEL
AD8512 / AD8512ARZ	AD8512 / AD8512ARZ-REEL	AD8512 / AD8512ARZ-REEL7	AD8512 / AD8512BRZ	AD8512 / AD8512BRZ-REEL
AD8512 / AD8512BRZ-REEL7	AD8512 / AD8512TRZ-EP	AD8512 / AD8512TRZ-EP-R7	AD8513 / AD8513ARUZ	AD8513 / AD8513ARUZ-REEL
AD8513 / AD8513ARZ	AD8513 / AD8513ARZ-REEL	AD8513 / AD8513ARZ-REEL7	AD8671 / AD8671ARMZ	AD8671 / AD8671ARMZ-REEL
AD8671 / AD8671ARZ	AD8671 / AD8671ARZ-REEL	AD8671 / AD8671ARZ-REEL7	AD8672 / AD8672ARMZ	AD8672 / AD8672ARMZ-REEL
AD8672 / AD8672ARZ	AD8672 / AD8672ARZ-REEL	AD8672 / AD8672ARZ-REEL7	AD8672 / AD8672TRZ-EP	AD8672 / AD8672TRZ-EP-R7
AD8674 / AD8674ARUZ	AD8674 / AD8674ARUZ-REEL	AD8674 / AD8674ARZ	AD8674 / AD8674ARZ-REEL	AD8674 / AD8674ARZ-REEL7
AD8682 / AD8682ARMZ	AD8682 / AD8682ARMZ-REEL	AD8682 / AD8682ARZ	AD8682 / AD8682ARZ-REEL	AD8682 / AD8682ARZ-REEL7
AD8684 / AD8684ARUZ	AD8684 / AD8684ARUZ-REEL	AD8684 / AD8684ARZ	AD8684 / AD8684ARZ-REEL	AD8684 / AD8684ARZ-REEL7
ADR01 / ADR01AKSZ-REEL7	ADR01 / ADR01ARZ	ADR01 / ADR01ARZ-REEL7	ADR01 / ADR01AUJZ-REEL7	ADR01 / ADR01BKSZ-REEL7
ADR01 / ADR01BRZ	ADR01 / ADR01BRZ-REEL7	ADR01 / ADR01BUJZ-REEL7	ADR01 / ADR01TUJZ-EP-R7	ADR02 / AD70/099Z-0
ADR02 / ADR02AKSZ-REEL7	ADR02 / ADR02ARZ	ADR02 / ADR02ARZ-REEL	ADR02 / ADR02ARZ-REEL7	ADR02 / ADR02AUJZ-REEL7
ADR02 / ADR02BRZ	ADR02 / ADR02BRZ-REEL7	ADR02 / ADR02BUJZ-REEL7	ADR03 / AD45302Z-R7	ADR03 / ADR03AKSZ-REEL7
ADR03 / ADR03ARZ	ADR03 / ADR03ARZ-REEL7	ADR03 / ADR03AUJZ-REEL7	ADR03 / ADR03BKSZ-REEL7	ADR03 / ADR03BRZ
ADR03 / ADR03BRZ-REEL7	ADR03 / ADR03BUJZ-REEL7	ADR03 / ADR03TKSZ-EP-R7	ADR06 / ADR06AKSZ-REEL7	ADR06 / ADR06ARZ
ADR06 / ADR06ARZ-REEL7	ADR06 / ADR06BKSZ-REEL7	ADR06 / ADR06BRZ	ADR06 / ADR06BRZ-REEL7	ADR06 / ADR06BUJZ-REEL7
ADR510 / ADR510ARTZ-REEL7	ADR525 / ADR525ARTZ-REEL7	ADR525 / ADR525BKSZ-REEL7	ADR525 / ADR525BRTZ-REEL7	ADR550 / ADR550ARTZ-REEL7
ADR550 / ADR550BRTZ-REEL7	MCPCHIPS / AD8510W	OP1177 / OP1177ARMZ	OP1177 / OP1177ARMZ-R7	OP1177 / OP1177ARMZ-REEL
OP1177 / OP1177ARZ	OP1177 / OP1177ARZ-REEL	OP1177 / OP1177ARZ-REEL7	OP282 / OP282ARMZ	OP282 / OP282ARMZ-REEL
OP282 / OP282GSZ	OP282 / OP282GSZ-REEL	OP282 / OP282GSZ-REEL7	OP482 / OP482GPZ	OP482 / OP482GSZ
OP482 / OP482GSZ-REEL	OP482 / OP482GSZ-REEL7	REF01 / REF01CPZ	REF01 / REF01CSZ	REF01 / REF01CSZ-REEL
REF01 / REF01CSZ-REEL7	REF01 / REF01HPZ	REF02 / REF02CPZ	REF02 / REF02CSZ	REF02 / REF02CSZ-REEL
REF02 / REF02CSZ-REEL7	REF02 / REF02HPZ	REF02 / REF02HSZ	REF03 / REF03GPZ	REF03 / REF03GSZ
REF03 / REF03GSZ-REEL7	SSM2019 / SSM2019BNZ	SSM2019 / SSM2019BRNZ	SSM2019 / SSM2019BRNZRL	SSM2019 / SSM2019BRWZ
SSM2019 / SSM2019BRWZRL				

Appendix B - Revision History:			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	01-Oct-2025	03-Jan-2026	Initial Release.



Reliability Report

Report Title: Qualification of ADI Camas Wafer Fab HVBP1 Processes for Non-Automotive Products

Report Number: 24457

Revision: C

Date: 15 September 2025

Summary

This report documents the reliability qualification requirements for the release of the HVBP1 wafer fabrication process for non-automotive products at Analog Devices Camas Wafer Fabrication Facility. The products listed below were selected to cover the technology being released.

The products are:

The AD8512 is a dual precision JFET amplifiers that feature low offset voltage, input bias current, input voltage noise, and input current noise.

The AD8672 is a very high precision amplifiers featuring very low noise, very low offset voltage and drift, low input bias current, 10 MHz bandwidth, and low power consumption. Output is stable with capacitive loads of over 1000 pF. Supply current is less than 3 mA per amplifier at 30 V.

Die/Fab Product Characteristics

Table 1: Die/Fab Product Characteristics- HVBP1

Product Characteristics	Product(s) used to be qualified	
Generic/Root Part #	AD8512	AD8672
Die Id	6W8512ARV 01	6W8672RV 01
Die Size (mm)	1.80 x 2.29	1.35 x 1.94
Wafer Fabrication Site	ADI-Camas	ADI-Camas
Wafer Fabrication Process	HVBP1	HVBP1
Die Substrate	Si	Si
Polyimide	No	No
Passivation	doped-oxide/SiN	doped-oxide/SiN

Die/Fab Test Results

Table 2: Die/Fab Test Results - HVBP1 at ADI-Camas

Test Name	Spec	Conditions	Generic/Root Part #	Lot #	Fail/SS
High Temperature Operating Life (HTOL)[1]	JESD22-A108	125°C<Tj<135°C, Biased, 1,000 Hours	AD8512	Q21237.1.HO1_RES	0/77
				Q21237.2.HO2_RES	0/77
				Q21237.3.HO3_RES	0/77
			AD8672	Q21248.1.HO1_RES	0/77
				Q21248.3.HO3_RES	0/77
High Temperature Storage Life (HTSL)	JESD22-A103	150°C, 1,000 Hours	AD8512	Q21237.1.HT1_RES	0/77
			AD8672	Q21248.1.HT1_RES	0/77
Highly Accelerated Temperature and Humidity Stress Test (HAST)[1]	JESD22-A110	130C 85%RH 33.3 psia, Biased, 96 Hours	AD8512	Q21237.1.HA1_RES	0/77
				Q21237.2.HA2_RES	0/77
				Q21237.3.HA3_RES	0/77
		110C 85%RH 17.7 psia, PWR CYC, P264	AD8672	Q21248.1.HA1_RES	0/77
Unbiased HAST (UHST)[1]	JESD22-A118	130C 85%RH 33.3 psia, 96 Hours	AD8512	Q21237.1.UH1_RES	0/77
				Q21237.2.UH2_RES	0/77
				Q21237.3.UH3_RES	0/77
			AD8672	Q21248.1.UH1_RES	0/77
				Q21248.2.UH2_RES	0/77
				Q21248.3.UH3_RES	0/77
Temperature Cycling (TC)[1]	JESD22-A104	-65°C/+150°C, 500 Cycles	AD8512	Q21237.1.TC1_RES	0/77
				Q21237.2.TC2_RES	0/77
				Q21237.3.TC3_RES	0/77
			AD8672	Q21248.1.TC1_RES	0/77
				Q21248.2.TC2_RES	0/77
				Q21248.3.TC3_RES	0/77

[1] These samples were subjected to preconditioning at MSL 1 with 3x reflow peak temp of 260°C prior to the start of the stress test.

Package/Assembly Product Characteristics

Table 3: Package/Assembly Product Characteristics - 8-SOIC_N at AMKOR (AP1)

Product Characteristics	Product(s) to be qualified	
Generic/Root Part #	AD8512	AD8672
Package	8-SOIC_N	8-SOIC_N
Body Size (mm)	4.90 x 3.90 x 1.375	4.90 x 3.90 x 1.375
Assembly Location	AMKOR (AP1)	AMKOR (AP1)
MSL/Peak Reflow Temperature(°C)	MSL 1 / 260°C	MSL 1 / 260°C
Mold Compound	Sumitomo G600	Sumitomo G600
Die Attach	Ablestik 84-1 LMISR4 conductive	Ablestik 84-1 LMISR4 conductive
Leadframe Material	Copper	Copper
Lead Finish	100 Sn	100 Sn
Wire Bond Material/Diameter (mils)	Gold / 1.20	2N Gold / 1.20

Package/Assembly Test Results

Table 4: Package/Assembly Product Characteristics - 8-SOIC_N at AMKOR (AP1)

Test Name	Spec	Conditions	Generic	Lot #	Fail/SS
Solder Heat Resistance (SHR)	J-STD-020	MSL1	AD8512	Q21237.1.SH1_RES	0/15
				Q21237.2.SH2_RES	0/15
				Q21237.3.SH3_RES	0/15
			AD8672	Q21248.1.SH1_RES	0/15
				Q21248.2.SH2_RES	0/15
				Q21248.3.SH3_RES	0/15
Highly Accelerated Temperature and Humidity Stress Test (HAST)[1]	JESD22-A110	130C 85%RH 33.3 psia, Biased, 96 Hours	AD8512	Q21237.1.HA1_RES	0/77
				Q21237.2.HA2_RES	0/77
				Q21237.3.HA3_RES	0/77
		110C 85%RH 17.7 psia, PWR CYC, P264	AD8672	Q21248.1.HA1_RES	0/77
Unbiased HAST (UHST)[1]	JESD22-A118	130C 85%RH 33.3 psia, 96 Hours	AD8512	Q21237.1.UH1_RES	0/77
				Q21237.2.UH2_RES	0/77
				Q21237.3.UH3_RES	0/77
			AD8672	Q21248.1.UH1_RES	0/77
				Q21248.2.UH2_RES	0/77
				Q21248.3.UH3_RES	0/77
Temperature Cycling (TC)[1]	JESD22- A104	-65°C/+150°C, 500 Cycles	AD8512	Q21237.1.TC1_RES	0/77
				Q21237.2.TC2_RES	0/77
				Q21237.3.TC3_RES	0/77
			AD8672	Q21248.1.TC1_RES	0/77
				Q21248.2.TC2_RES	0/77
				Q21248.3.TC3_RES	0/77

[1] These samples were subjected to preconditioning at MSL 1 with 3x reflow peak temp of 260°C prior to the start of the stress test.

ESD and Latch-Up Test Results

Table 5: ESD Test Result

ESD Model	Generic/Root Part #	Package	ESD Test Spec	RC Network	Highest Pass Level	Class
FICDM	AD8512	8-SOIC_N	JS-002	1Ω, Cpkg	±1250V	C3
	AD8672				±1500V	C3
HBM	AD8512	8-SOIC_N	JS-001	1.5kΩ, 100pF	±4000V	3A
	AD8672				±4000V	3A

Table 6: Latch Up Test Result

LU Test Spec	Generic/Root Part #	Passing Current	Passing Over-Voltage	Temperature (T_A)	Class
JESD78	AD8512	+100mA, -100mA	+22.5V	25°C	I
JESD78	AD8672	+100mA, -100mA	+22.5V	25°C	I

Approvals

Reliability Engineer: